

IN THE CLAIMS:

Claims 1-15 and 26-33 were previously cancelled. Claims 16, 20, 21 and 24 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1.-15. (Cancelled)

16. (Currently amended) A method of making an IC chip package having a first IC chip with an active surface, the active surface having ~~extending therefrom~~ an electrical connector extending therefrom in electrical communication with the first IC chip, the first IC chip being mounted upon a first side of a board-on-chip (BOC) substrate having ~~said~~ the first side that is opposite a second side thereof, the method comprising:

providing a second IC chip having an active surface and being disposed over the first side of the BOC substrate;

providing a container disposed upon the BOC substrate, the container in contact with the active surface of the first IC chip; and

injecting a grease between the BOC substrate and the container;

wherein the grease:

is in contact with the electrical connector and with the active surfaces of each of the first and second IC chips; and

is enclosed within the container and the BOC substrate.

17. (Original) The method as defined in Claim 16, further comprising:
providing a third IC chip having an active surface and being disposed over the first side of the BOC substrate and over the second IC chip such that the grease is in contact with the active surface of the third IC chip.

18. (Previously presented) The method as defined in Claim 17, further comprising:
operating the first, second, and third IC chips to generate heat therefrom; and
conducting the heat from the electrical connector and from the first, second, and third IC chips to the grease, to the container, and to the ambient.

19. (Original) The method as defined in Claim 16, wherein the grease has:
a thermal conductivity in a range from about 2 Watts/m·K to about 5 Watts/m·K;
a dielectric constant in a range from less than about 6 to about 9; and
a melting point in a range from about 190° C to about 220° C.

20. (Currently amended) The method as defined in ~~in-claim~~ Claim 16, further comprising:
generating heat from at least one of the first or second IC chips by operating ~~said the~~ at least one of the IC chips; and
allowing the heat to propagate to the grease and to the container.

21. (Currently amended) The method as defined in Claim 16, further comprising:
securing the container to the BOC substrate with a dam structure that contacts the grease.

22. (Previously Presented) The method as defined in Claim 16, further comprising:
operating the first and second IC chips to generate heat therefrom; and
conducting the heat from the IC chips and the electrical connector to the grease, to the container, and to the ambient.

23. (Previously Presented) The method as defined in Claim 16, wherein the grease has a thermal conductivity that is less than a thermal conductivity of the container.

24. (Currently amended) The method as defined in Claim 16, wherein the IC chip package comprises IC chip elements, wherein the container disposed upon the BOC substrate encloses a volume external to the IC chip elements, and wherein the injecting a grease comprises filling with the grease the volume enclosed by the container.

25. (Previously Presented) The method as defined in Claim 16, wherein the container comprises a metal that has a thermal conductivity greater than the thermal conductivity of the grease.

26.-33. (Cancelled)